

## PATENT ASSIGNMENT COVER SHEET

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Stylesheet Version v1.2

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| SUBMISSION TYPE:   | NEW ASSIGNMENT                  |
| NATURE OF CONVEYANCE:  | ASSIGNMENT                      |
| CONVEYING PARTY DATA   |                                 |
| Name   | Execution Date                  |
| TIM MOBLEY   | 01/08/2014                      |
| RECEIVING PARTY DATA   |                                 |
| Name:  | NMODE SOLUTIONS, INC.           |
| Street Address:  | 8950 N. ORACLE RD.              |
| Internal Address:  | SUITE 100                       |
| City:  | ORO VALLEY                      |
| State/Country:   | ARIZONA                         |
| Postal Code:   | 85704                           |
| PROPERTY NUMBERS Total: 1  |                                 |
| Property Type  | Number                          |
| Application Number:  | 13666089                        |
| CORRESPONDENCE DATA  |                                 |
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| <i>Correspondence will be sent via US Mail when the email attempt is unsuccessful.</i> |                                 |
| Correspondent Name:  | ROCHELLE ROTEA                  |
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| Address Line 4:  | MOUNTAIN VIEW, CALIFORNIA 94040 |
| ATTORNEY DOCKET NUMBER:  | NMODE-001                       |
| NAME OF SUBMITTER:   | ADRIENA M. GARCIA               |
| Signature:   | /Adriena M. Garcia/             |
| Date:  | 01/13/2014                      |
| Total Attachments: 1<br>source=NMODE-001_Assignment#page1.tif                          |                                 |

# ASSIGNMENT

THIS ASSIGNMENT, by Tim Mobley (hereinafter referred to as the Assignor), witnesseth:

WHEREAS, said Assignor has invented certain new and useful improvements, which are described in United States patent application 13/666,089 entitled **Low Cost and High Performance Bonding of Wafer to Interposer & Method of Forming Vias and Circuits** and filed November 1, 2012;

WHEREAS nMode Solutions, Inc., a body having a principal place of business at 1840 E. River Road, Suite 201, Tucson, Arizona 85718 (hereinafter referred to as the Assignee), is desirous of obtaining the entire right, title and interest in and to said inventions and said applications for Letters Patent, and in and to any Letters Patent, United States or foreign, to be obtained therefore and thereon, and to any and all improvements which are disclosed in said applications for Letters Patent;

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged:

1. The Assignor has sold, assigned, transferred, and set over, and does hereby sell, assign, transfer, and set over unto said Assignee the entire right, title, and interest in, to, and under said inventions; said applications for Letters Patent; any Letters Patent which may be granted for said inventions in the United States of America and any foreign country; any division, continuation, and continuation-in-part of said applications; any reissue or extension of said Letters Patent; and all rights under the International Convention for the Protection of Industrial Property; said right, title, and interest to be held and enjoyed by said Assignee for its own use and behoove to the full end of the term for which Letters Patent may be granted, as fully and entirely as the same would have been held and enjoyed by the Assignor, had this sale and assignment not been made.

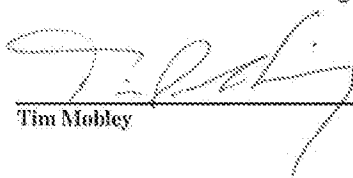
2. Said Assignor hereby warrants and represents that, at the time of execution and delivery of these presents, said Assignor was the lawful owner of the entire right, title, and interest in and to said inventions and said applications for Letters Patent, and that the same had not entered into any assignment, contract or understanding in conflict herewith.

3. Said Assignor hereby covenants and agrees to assist and cooperate with said Assignee, whereby said Assignee may enjoy to the fullest extent said right, title, and interest herein conveyed, provided, however, that the entire expense which may be incurred by said Assignor in lending such assistance and cooperation be paid by Assignee. Such cooperation shall include: (a) prompt execution of all papers (prepared at the expense of Assignee) that are deemed necessary or desirable by Assignee to perfect said right, title and interest herein conveyed, (b) prompt execution of all petitions, oaths, specifications, declarations and other papers (prepared at the expense of Assignee) that are deemed necessary or desirable by Assignee for filing or prosecuting in the United States or any foreign country said applications, any applications which are a division, continuation, or continuation-in-part of said applications, any reissue application for any Letters Patent granted on said applications, or for any interference proceeding involving said applications or Letters Patent granted thereon; and (c) prompt assistance and cooperation in the prosecution of all legal proceedings involving said inventions, said applications, or Letters Patent granted thereon, including oppositions, cancellation proceedings, priority contests, public use proceedings, and court actions.

4. The terms, covenants and conditions of this Assignment shall inure to the benefit of said Assignee, its successors, assigns, and/or other legal representatives, and shall be binding upon said Assignor, his/her heirs, legal representatives, and assigns.

5. Said Assignor hereby requests the Commissioner of Patents and Trademarks to issue said Letters Patent of the United States to said Assignee as the Assignee of said inventions.

IN WITNESS WHEREOF said Assignor has executed and delivered this instrument on the date noted below.

  
\_\_\_\_\_  
Tim Mobley

  
\_\_\_\_\_  
Date